

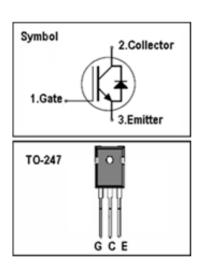
#### **IGBT**

#### **Features**

- 650V,20A
- $V_{CE(sat)(typ.)}$ =2.0V@ $V_{GE}$ =15V, $I_{C}$ =20A
- High speed switching
- Higher system efficiency
- Soft current turn-off waveforms
- Square RBSOA

#### **General Description**

JIAEN Trench IGBTs offer lower losses and higher energy efficiency for application such as Motor control, general inverter and other soft switching applications.



## **Absolute Maximum Ratings**

Symbol	Parameter	Value	Units	
Vces	Collector-Emitter Voltage 650			
V <sub>GES</sub>	Gate-Emitter Voltage	<u>+</u> 30 V		
1-	Continuous Collector Current ( Tc=25 °C)		А	
lc	Continuous Collector Current (Tc=100°C)	20	А	
Ісм	Pulsed Collector Current (Note 1) 60		А	
I <sub>F</sub>	Diode Continuous Forward Current ( T <sub>C</sub> =100 °C) 20		А	
I <sub>FM</sub>	Diode Maximum Forward Current (Note 1)	60 A		
t <sub>sc</sub>	Short Circuit Withstand Time	10 us		
D-	Maximum Power Dissipation ( $T_C=25 ^{\circ}\mathrm{C}$ )	156	W	
P <sub>D</sub>	Maximum Power Dissipation ( T <sub>C</sub> =100°C)	63	W	
TJ	Operating Junction Temperature Range	-55 to +150 °C		
Tstg	Storage Temperature Range	rature Range -55 to +150 °C		

#### **Thermal Characteristics**

Symbol	Parameter	Max.	Units
R <sub>th j-c</sub> Thermal Resistance, Junction to case for IGBT 0.8 °C/			
R <sub>th j-c</sub>	R <sub>th j-c</sub> Thermal Resistance, Junction to case for Diode 1.6 °C/ W		°C/W
R <sub>th j-a</sub> Thermal Resistance, Junction to Ambient 40		°C/W	



## $\underline{\textbf{Electrical Characteristics}} \text{ (Tc=25\,°C unless otherwise noted )}$

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Units
BV <sub>CES</sub>	Collector-Emitter Breakdown Voltage	$V_{GE} = 0V, I_{C} = 250uA$	650	-	-	V
I <sub>CES</sub>	Collector-Emitter Leakage Current	V <sub>CE</sub> = 650V, V <sub>GE</sub> = 0V	-	-	100	uA
I <sub>GES</sub>	Gate Leakage Current, Forward	$V_{GE}$ = $\pm 20V$ , $V_{CE}$ = $0V$	-	-	±100	nA
$V_{GE(th)}$	Gate Threshold Voltage	$V_{GE} = V_{CE}$ , $I_C = 250uA$	5.1	-	6.9	V
V <sub>CE(sat)</sub>	Collector-Emitter Saturation Voltage	$V_{GE}$ =15V, $I_{C}$ = 20A	-	2.0	2.5	V
Qg	Total Gate Charge	Vcc=480V	-	271		nC
Q <sub>ge</sub>	Gate-Emitter Charge	V <sub>GE</sub> =15V	-	70		nC
Qgc	Gate-Collector Charge	Ic=20A	-	131		nC
t d(on)	Turn-on Delay Time	Vcc=400V	-	17	-	ns
t r	Turn-on Rise Time		-	31	-	ns
t d(off)	Turn-off Delay Time	V <sub>GE</sub> =15V	-	71	-	ns
t f	Turn-off Fall Time	1l <sub>C</sub> =20A R <sub>G</sub> =15Ω	-	99	-	ns
Eon	Turn-on Switching Loss	Inductive Load	-	0.46	-	mJ
Eoff	Turn-off Switching Loss	T <sub>C</sub> =25 ℃	-	0.41	-	mJ
Ets	Total Switching Loss		-	0.87	-	mJ
C <sub>ies</sub>	Input Capacitance	V <sub>CE</sub> =25V V <sub>GE</sub> =0V	-	831	-	pF
Coes	Output Capacitance		-	50	-	pF
C <sub>res</sub>	Reverse Transfer Capacitance	f = 1MHz	-	7.5	-	pF

# $\underline{\textbf{Electrical Characteristics of Diode}}_{(T_C=25\,{}^{\circ}\!\text{C unless otherwise noted })}$

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Units
V <sub>F</sub>	Diode Forward Voltage	I <sub>F</sub> =20A	-	1.5	3.0	V
trr	Diode Reverse Recovery Time	V <sub>CE</sub> = 400V	-	110		ns
Irr	Diode peak Reverse Recovery Current	I <sub>F</sub> = 20A	-	16.6		Α
Qrr	Diode Reverse Recovery Charge	Rg=15 Ω	-	736		nC

#### Notes:

1. Repetitive Rating: Pulse width limited by maximum junction temperature



## **Typical Performance Characteristics**

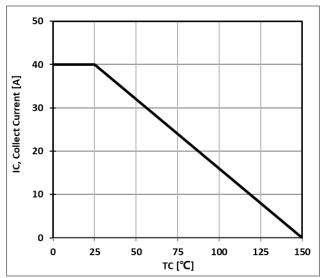


Figure 1: Maximum DC Collector Current VS. case temprature

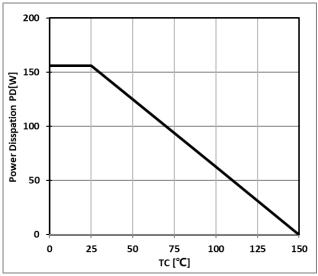


Figure 2: Power Dissipation VS. Case Temperature

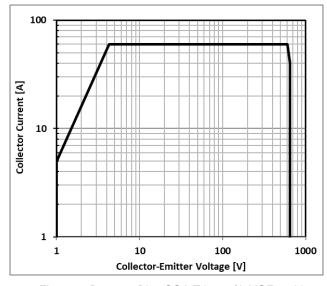


Figure 3: Reverse Bias SOA,TJ=125℃,VGE=15V

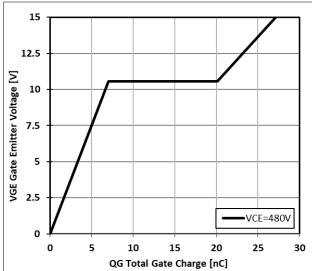


Figure 4: Typical Gate charge VS. VGE,IC=20A



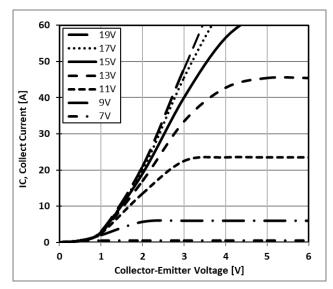


Figure 5: Typical IGBT Output characteristics,  $TC=25^{\circ}C$ ;tp=300us

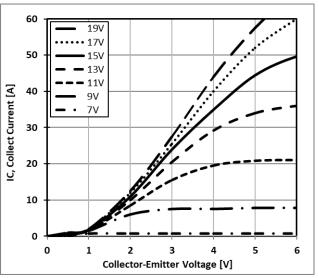


Figure 6: Typical IGBT Output characteristics, TC=150°C;tp=300us

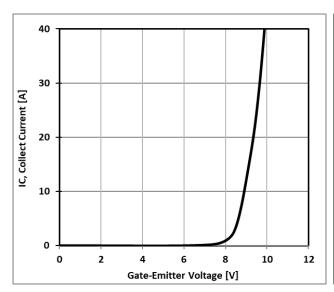


Figure 7: Typical Gate Threshold Voltage

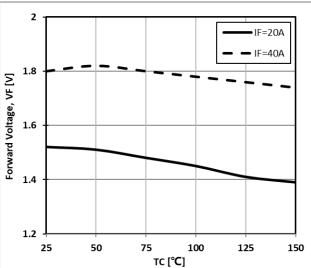


Figure 8: Typical Forward Voltage vs IF



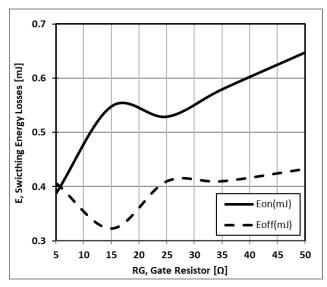


Figure 9: Typical Energy Loss VS. RG, TC=25 °C, L=200uH,VCE=400V,VGE=15V,IC=20A

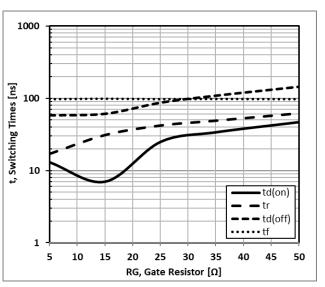


Figure 10: Typical Switching Time VS. RG, TC=25°C, L=200uH,VCE=400V,VGE=15V,IC=20A

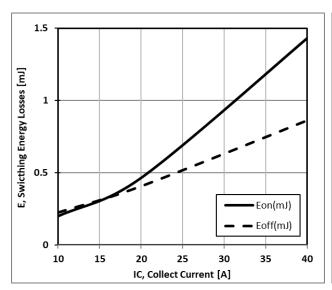


Figure 11: Typical Energy Loss VS. IC,TC=25  $^{\circ}$ C, L=200uH, VCE=400V, VGE=15V,RG=15  $^{\Omega}$ 

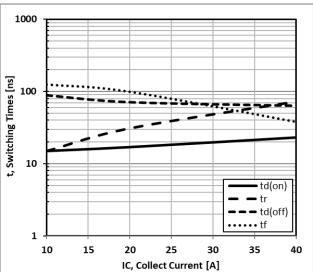


Figure 12: Typical Switching Time VS. IC,TC=25 $^{\circ}$ C, L=200uH,VCE=400V,VGE=15V,RG=15 $^{\circ}$ 



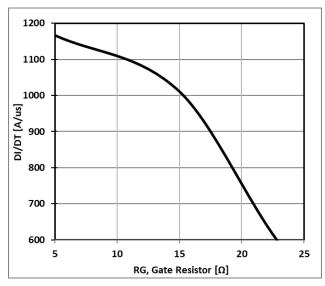


Figure 13: Typical Diode DI/DT VS. RG,TC=25°C VCC=400V, VGE=15V, IF=20A

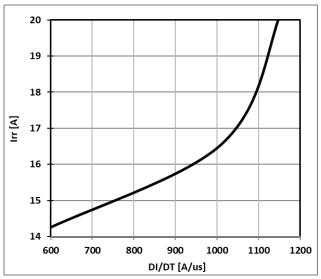


Figure 14: Typical Diode IRR VS. DI/DT,TC=25°C VCC=400V,VGE=15V, IF=20A

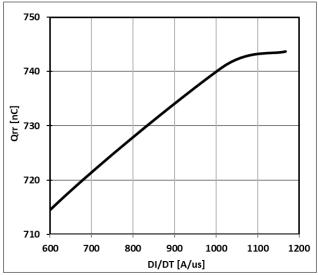


Figure 15: Typical Diode Qrr VS. DI/DT,TC=25℃ VCC=400V, VGE=15V, IF=20A

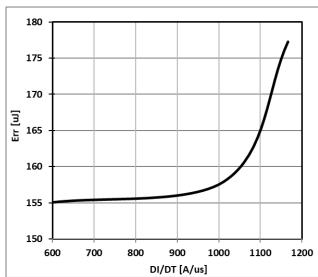


Figure 16: Typical Diode Err VS. DI/DT,TC= $25^{\circ}$ C VCC=400V, VGE=15V, IF=20A



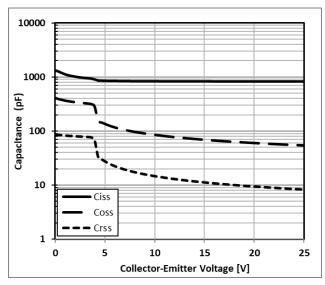


Figure 17: Typical Capacitance VS. VCE,  $VGE {=} 0V, f {=} 1MHz \label{eq:VGE}$ 

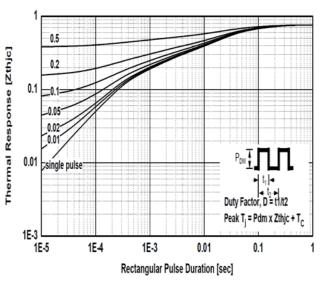
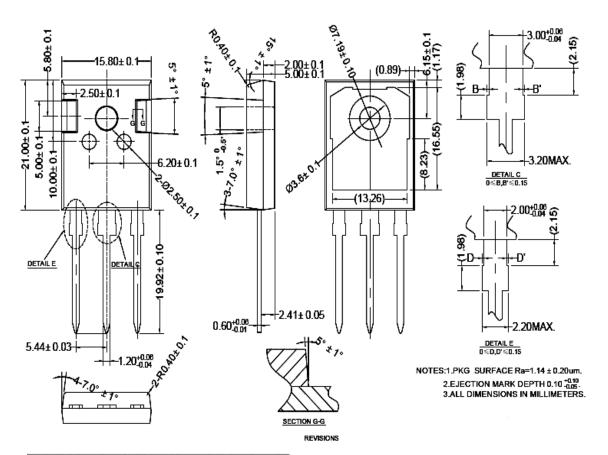


Figure 18: Normalized transient thermal impedance junction-to-case



#### **TO-247 PACKAGE OUTLINE**



公差标注	会差值	表面粗糙度
0	±0.2	Ra3.2~6.3
0.0	±0.1	Ra1.6~3.2
0.00	±0.01	Ra0.8~1.6
0.000	±0.005	Ra0.4~0.8
0.0000	±0.002	Ra0.2~0.4

0≤D,D'≤0.15

NOTES:1.PKG SURFACE Ra=1.14 ± 0.20um. 2.EJECTION MARK DEPTH 0.10 ±0.05 3.ALL DIMENSIONS IN MILLIMETERS.



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